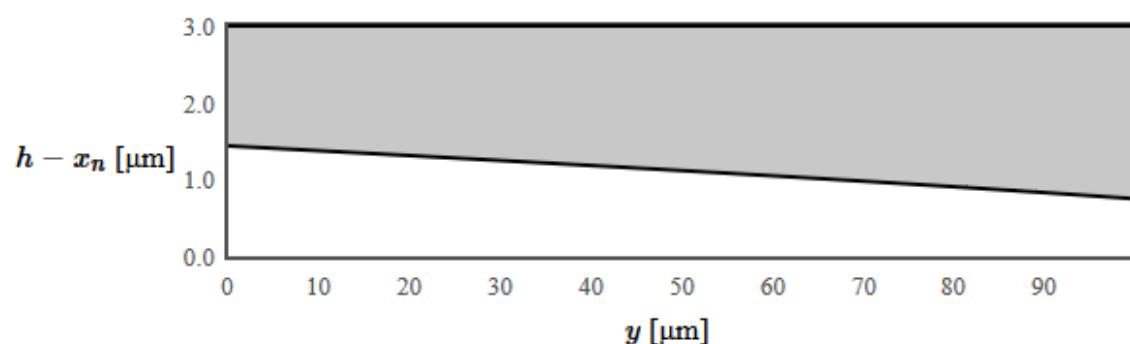
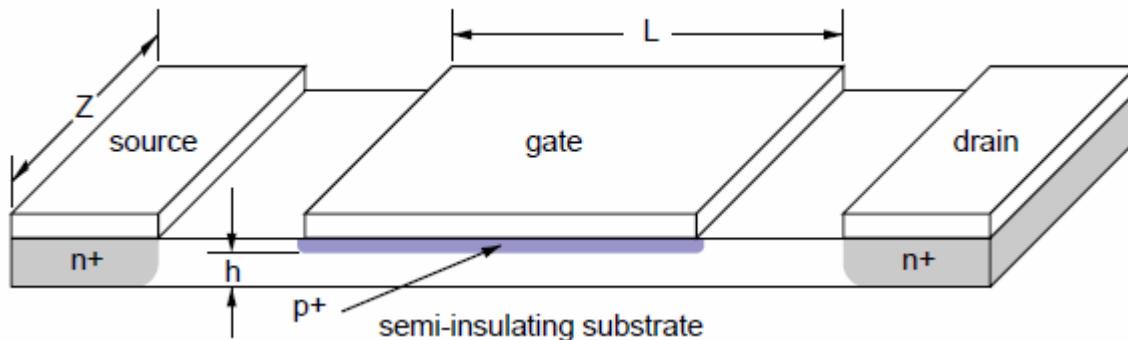


9. JFETs / MESFETS /MODFETs

Nov. 27, 2019

JFET Gradual Channel Approximation

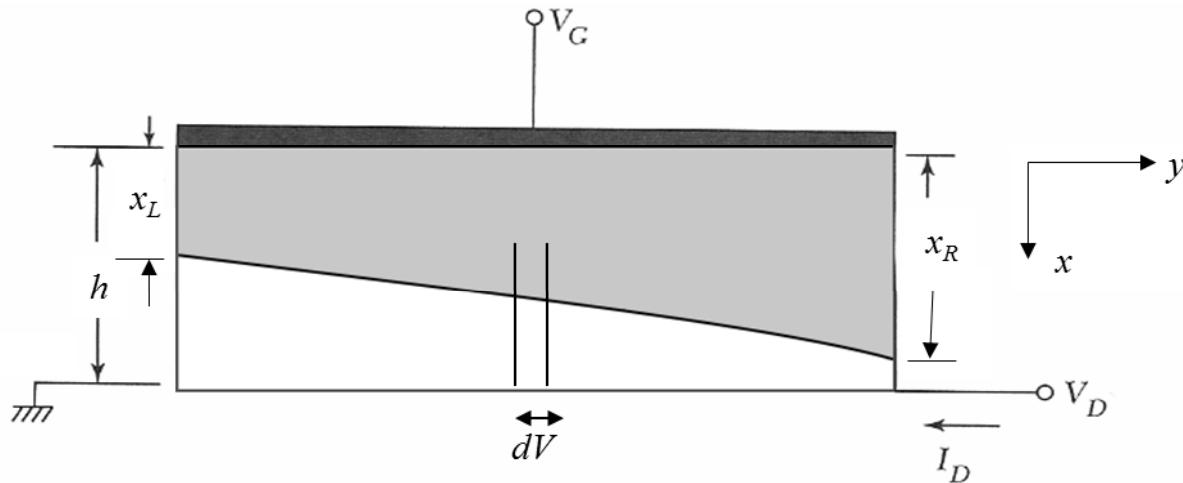


$N_c(300K) =$	2.78E19	cm^{-3}
$N_v(300K) =$	9.84E18	cm^{-3}
$E_g =$	$1.166 - 4.73E-4 * T^2 / (T + 636)$	eV
$N_D =$	1E15	cm^{-3}
$N_A =$	1E19	cm^{-3}
$\mu_n =$	1350	cm^2/Vs
$h =$	3	μm
$L =$	100	μm
$Z =$	100	μm
$\epsilon_r =$	11.9	
$T =$	300	K
$V_D =$	2	V
$V_g =$	-1	V

Replot

Si Ge GaAs

JFET

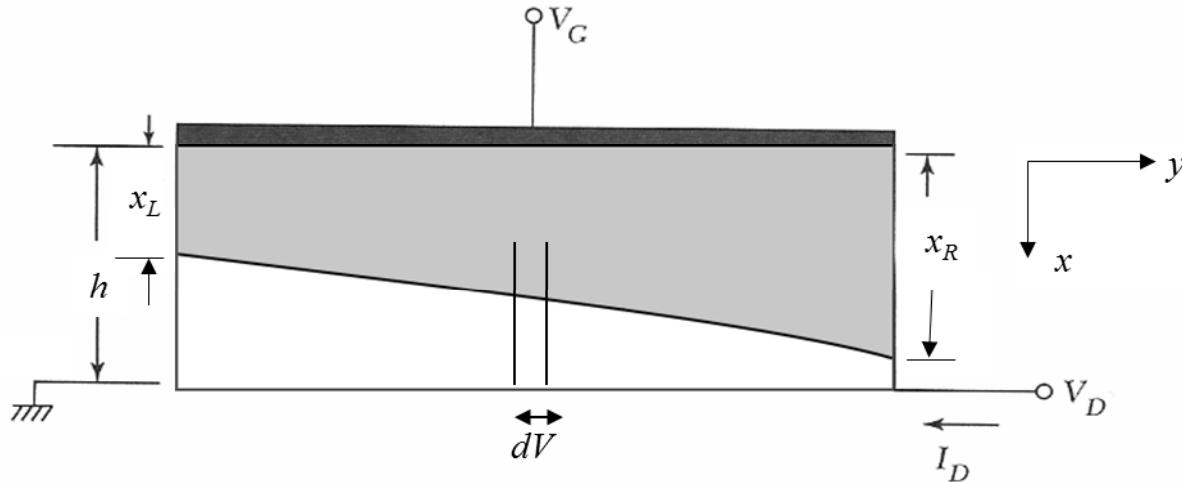


There is a long derivation to determine how the current depends on V_G and V_D .

We will find a relatively simple formula (probably familiar to electrical engineers).

Understanding the derivation is important for knowing when this formula is valid.

JFET



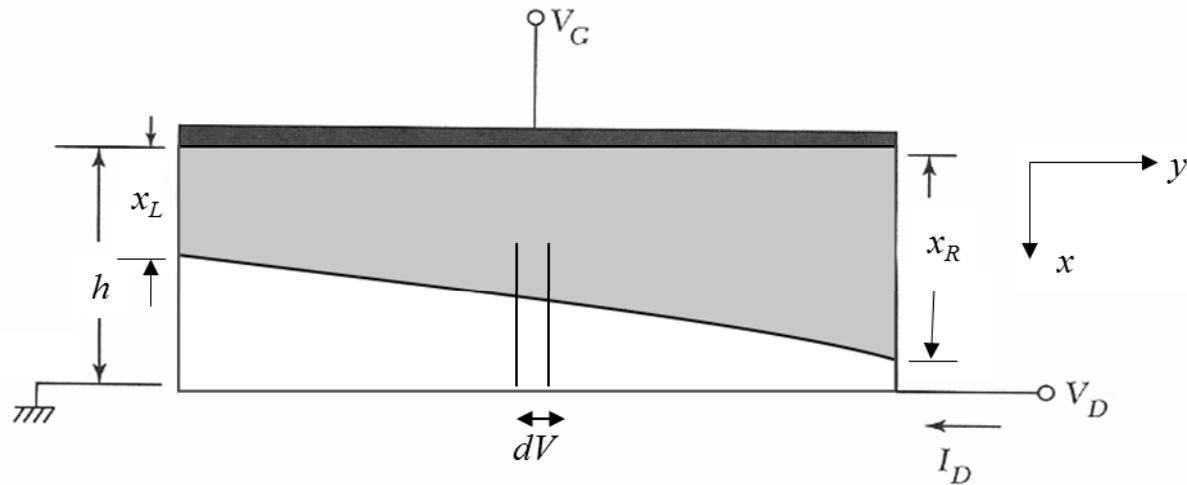
$$dV = I_D dR = I_D \frac{\rho dy}{Z(h - x_n(y))}$$

$$\rho = \frac{1}{\sigma} = \frac{1}{ne\mu_n} = \frac{1}{N_D e \mu_n}$$

$$\frac{dV}{dy} = \frac{I_D}{e\mu_n N_D Z(h - x_n(y))} = -E_y$$

JFET

$$I_D dy = e \mu_n N_D Z(h - x_n(y)) dV$$



V_G is a forward bias
 $V(y)$ is a reverse bias.

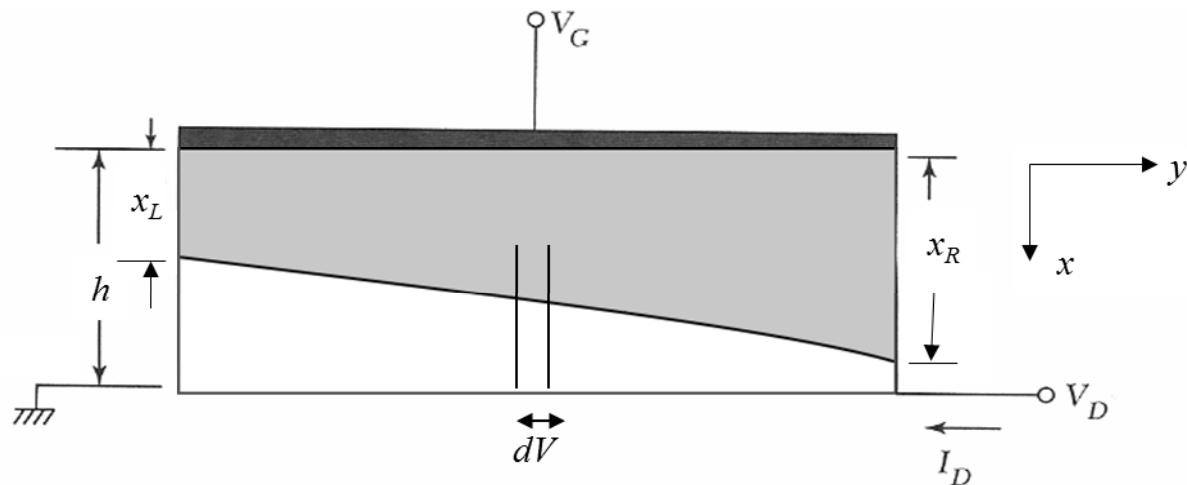
depletion width is a function of position

$$x_n(y) = \sqrt{\frac{2\epsilon(V_{bi} + V(y) - V_G)}{eN_D}}$$

differentiate $\frac{dx_n(y)}{dV} =$

JFET

$$I_D dy = e \mu_n N_D Z(h - x_n(y)) dV$$



V_G is a forward bias
 $V(y)$ is a reverse bias.

depletion width is a function of position

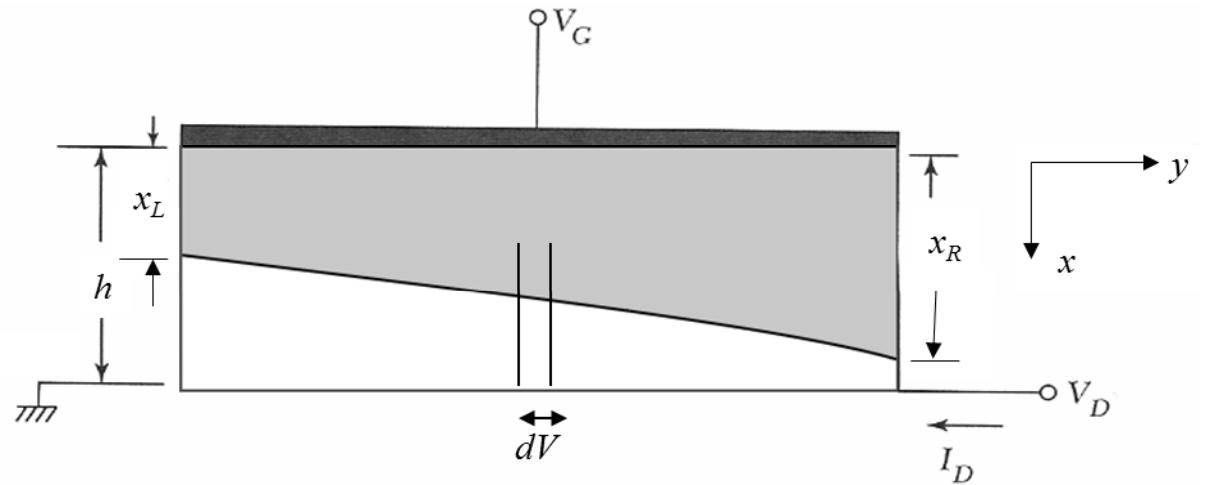
$$x_n(y) = \sqrt{\frac{2\epsilon(V_{bi} + V(y) - V_G)}{eN_D}}$$

differentiate

$$\frac{dx_n(y)}{dV} = \frac{1}{2} \left(\frac{2\epsilon(V_{bi} + V(y) - V_G)}{eN_D} \right)^{-1/2} \frac{2\epsilon}{eN_D} = \frac{\epsilon}{eN_D x_n(y)}$$

$$dV = \frac{eN_D x_n}{\epsilon} dx_n$$

JFET



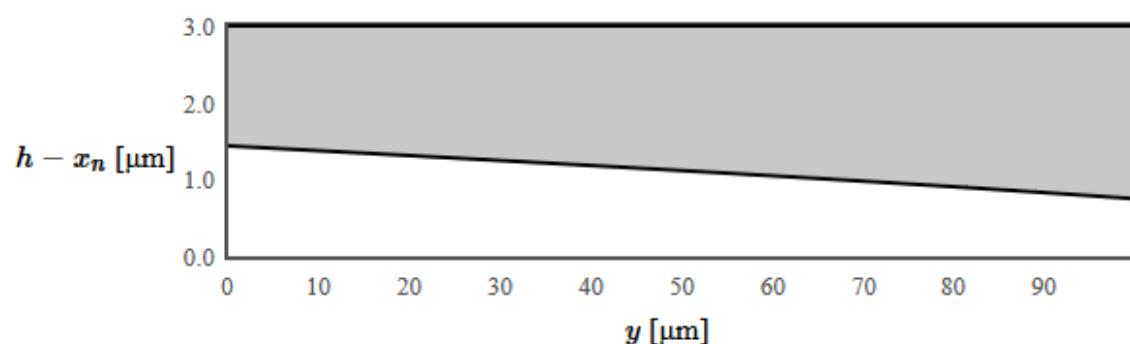
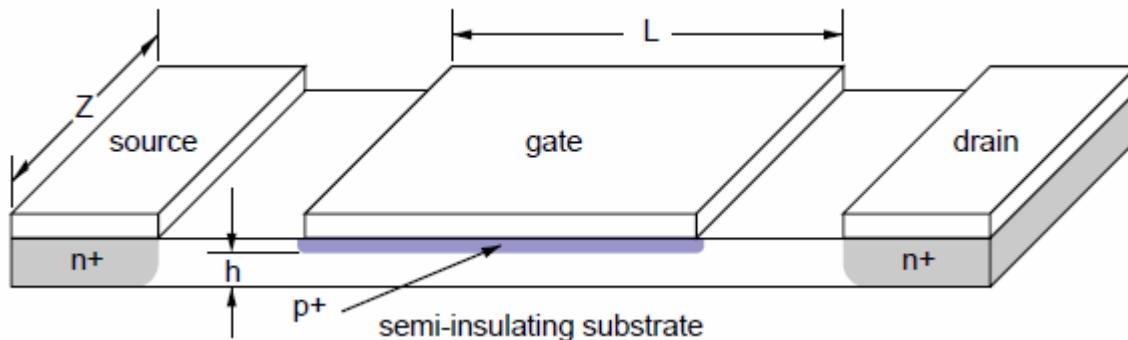
$$I_D dy = e\mu_n N_D Z(h - x_n(y)) dV \quad \text{from last slide}$$

$$dV = \frac{eN_D x_n}{\epsilon} dx_n$$

$$\frac{dx_n(y)}{dy} = \frac{I_D}{e\mu_n N_D Z(h - x_n(y)) \frac{eN_D}{\epsilon} x_n(y)}$$

If I_D is known, this can be solved for $x_n(y)$.

JFET Gradual Channel Approximation



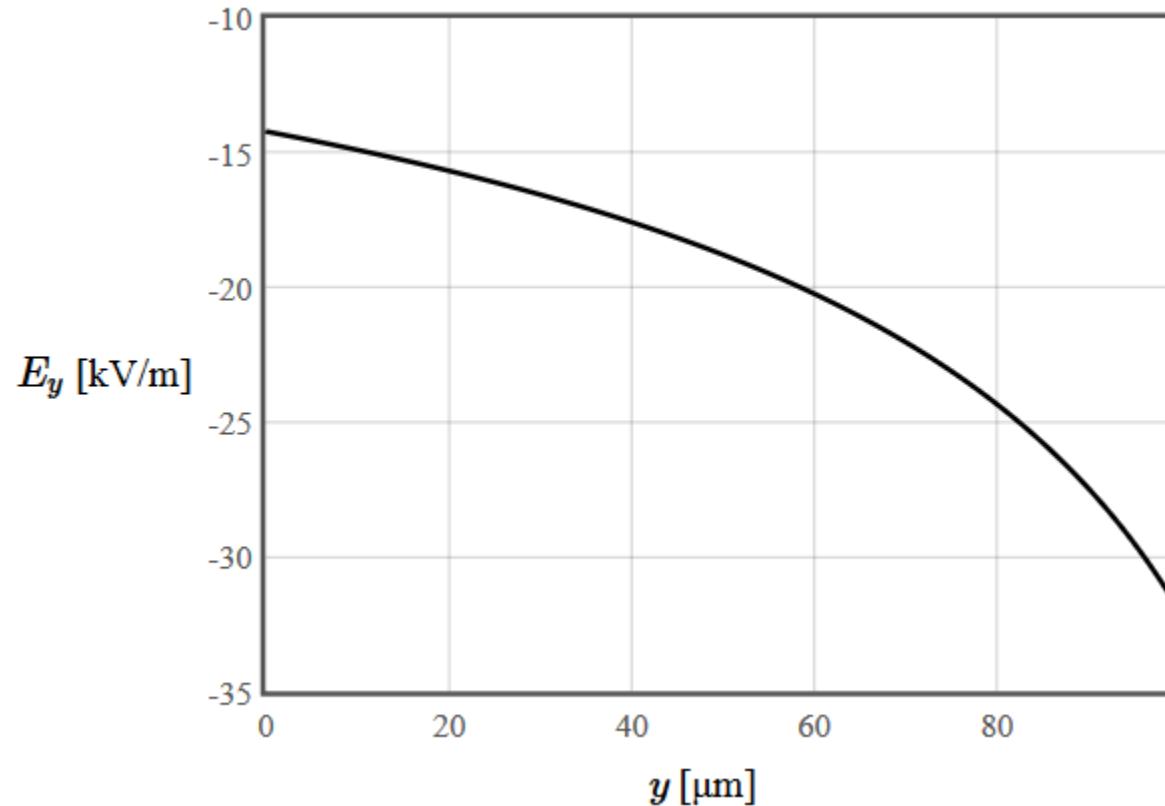
$N_c(300K) =$	2.78E19	cm^{-3}
$N_v(300K) =$	9.84E18	cm^{-3}
$E_g =$	1.166-4.73E-4*T*T/(T+636)	eV
$N_D =$	1E15	cm^{-3}
$N_A =$	1E19	cm^{-3}
$\mu_n =$	1350	cm^2/Vs
$h =$	3	μm
$L =$	100	μm
$Z =$	100	μm
$\epsilon_r =$	11.9	
$T =$	300	K
$V_D =$	2	V
$V_g =$	-1	V

Replot

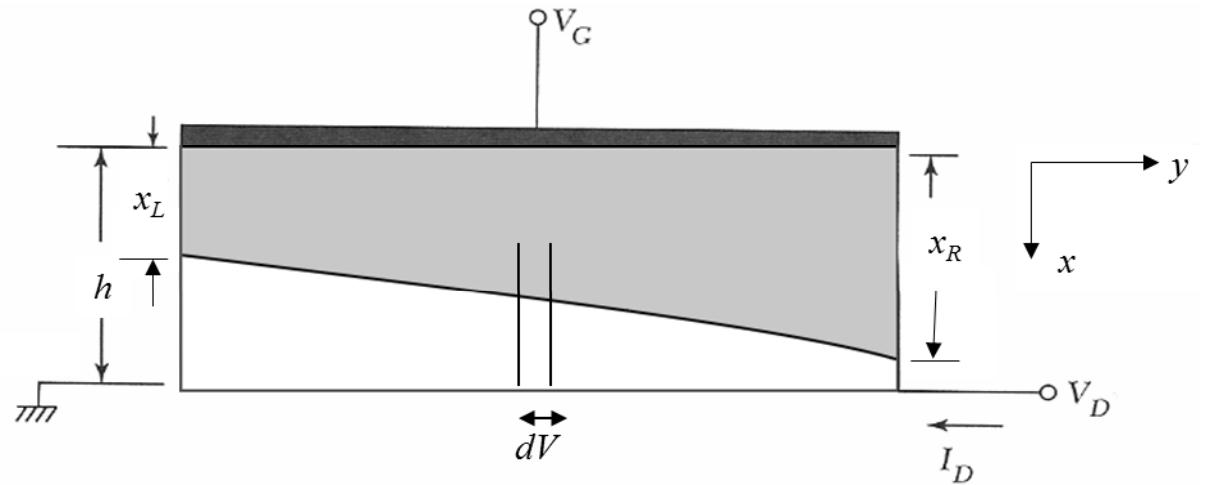
Si Ge GaAs

Electric field

$$\frac{dV}{dy} = \frac{I_D}{e\mu_n N_D Z(h - x_n(y))} = -E_y$$



JFET

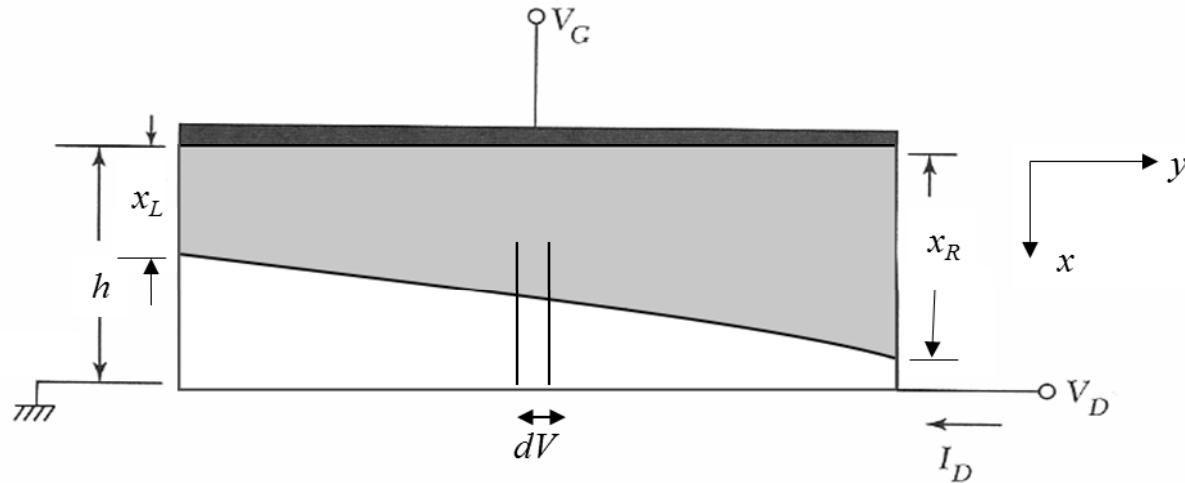


$$I_D dy = e \mu_n N_D Z (h - x_n(y)) \frac{e N_D}{\epsilon} x_n dx_n$$

$$I_D \int_0^L dy = e \mu_n N_D Z \frac{e N_D}{\epsilon} \int_{x_L}^{x_R} (h - x_n(y)) x_n dx_n$$

$$I_D = \frac{\mu_n N_D^2 Z e^2}{2 L \epsilon} \left[h \left(x_R^2 - x_L^2 \right) - \frac{2}{3} \left(x_R^3 - x_L^3 \right) \right]$$

JFET



$$I_D = \frac{\mu_n N_D^2 Z e^2}{2 L \epsilon} \left[h \left(x_R^2 - x_L^2 \right) - \frac{2}{3} \left(x_R^3 - x_L^3 \right) \right]$$

$$h = \sqrt{\frac{2\epsilon V_p}{e N_D}} \quad x_L = \sqrt{\frac{2\epsilon(V_{bi} - V_G)}{e N_D}} \quad x_R = \sqrt{\frac{2\epsilon(V_{bi} - V_G + V_D)}{e N_D}}$$

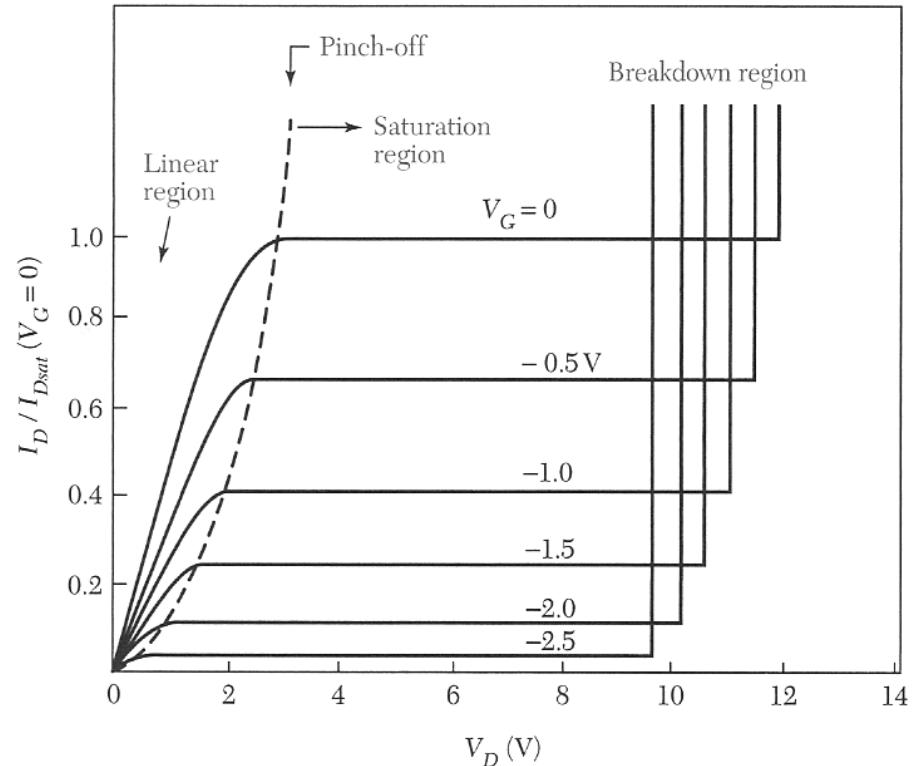
$$V_p = \frac{e N_D h^2}{2 \epsilon_r \epsilon_0}$$

JFET - drain current

$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

$$I_p = \frac{\mu_n N_D^2 Z e^2 h^3}{2 L \epsilon}$$

valid in the linear regime
(until pinch-off)



JFET - Linear regime

$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

In the linear regime $V_D \ll V_{sat}$.

$$\frac{dI_D}{dV_D} =$$

JFET - Linear regime

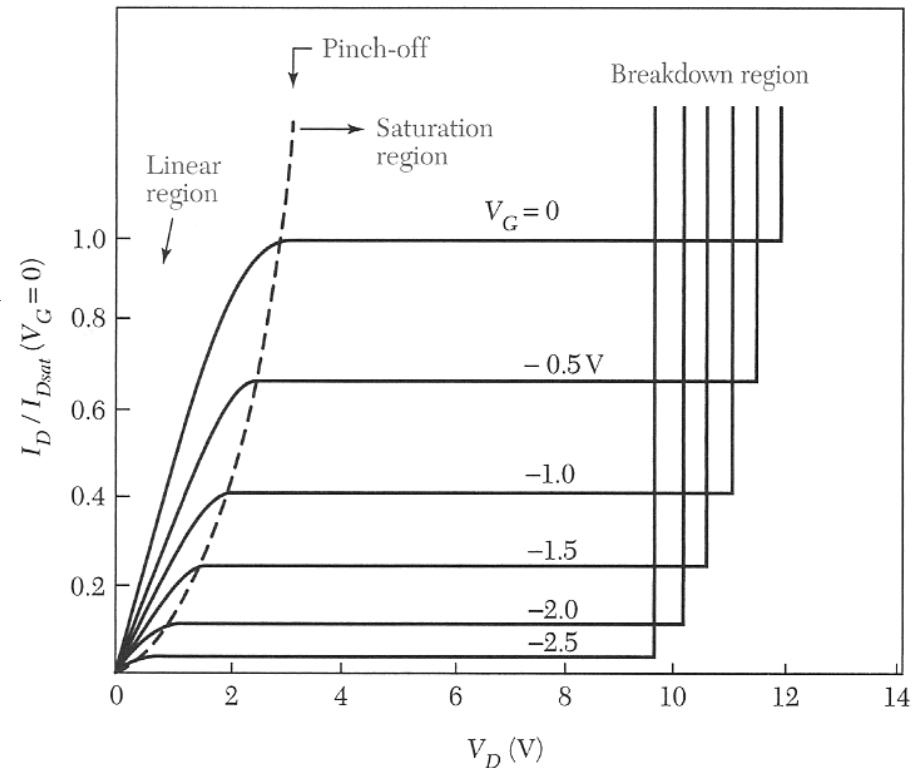
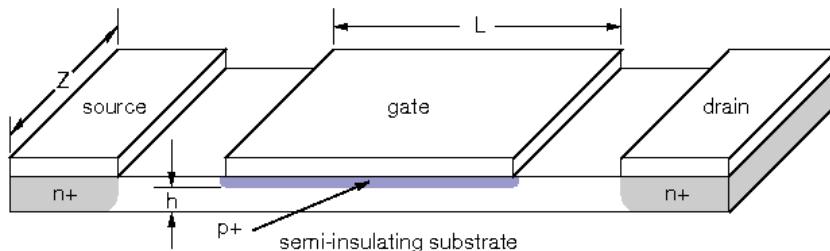
$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

In the linear regime $V_D \ll V_{sat}$.

$$\frac{dI_D}{dV_D} = I_p \left[\frac{1}{V_p} - \frac{1}{V_p} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{1/2} \right]$$

$$I_D = \frac{I_p}{V_p} \left[1 - \sqrt{\frac{V_{bi} - V_G}{V_p}} \right] V_D \text{ for } V_D \ll V_{sat}$$

variable resistor



JFET - Saturation regime

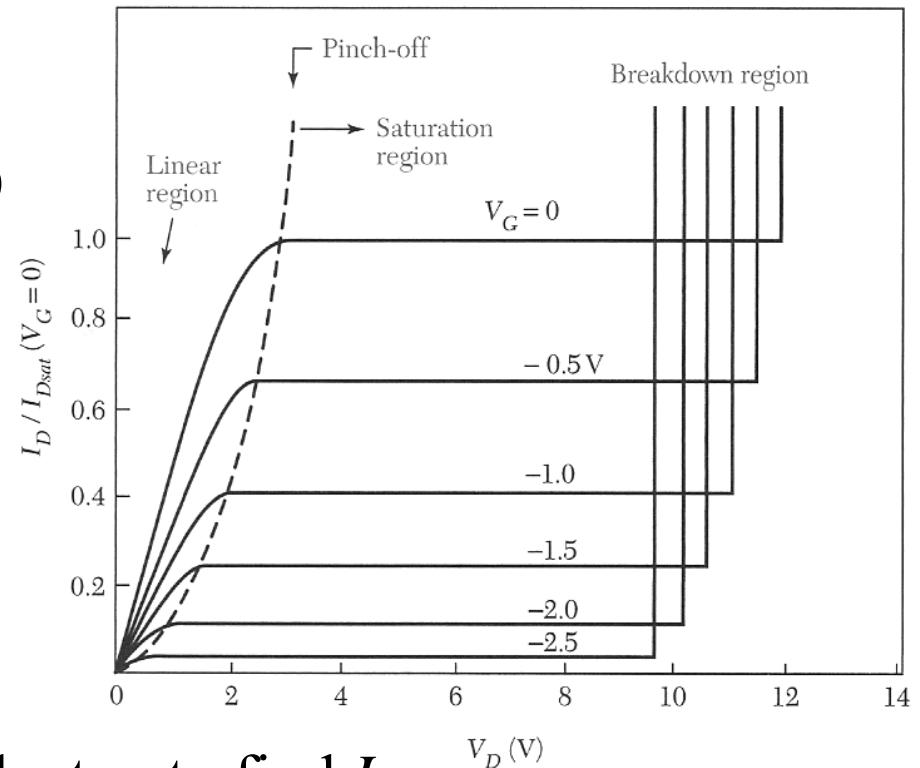
$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

set $dI_D/dV_D = 0$ to find V_{sat}

$$\frac{dI_D}{dV_D} = I_p \left[\frac{1}{V_p} - \frac{1}{V_p} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{1/2} \right] = 0$$

$$dI_D/dV_D = 0 \text{ when } \frac{V_{bi} + V_D - V_G}{V_p} = 1$$

$$V_{sat} = V_p - V_{bi} + V_G$$



Substitute V_{sat} into the equation at the top to find I_{sat}

JFET - Saturation regime

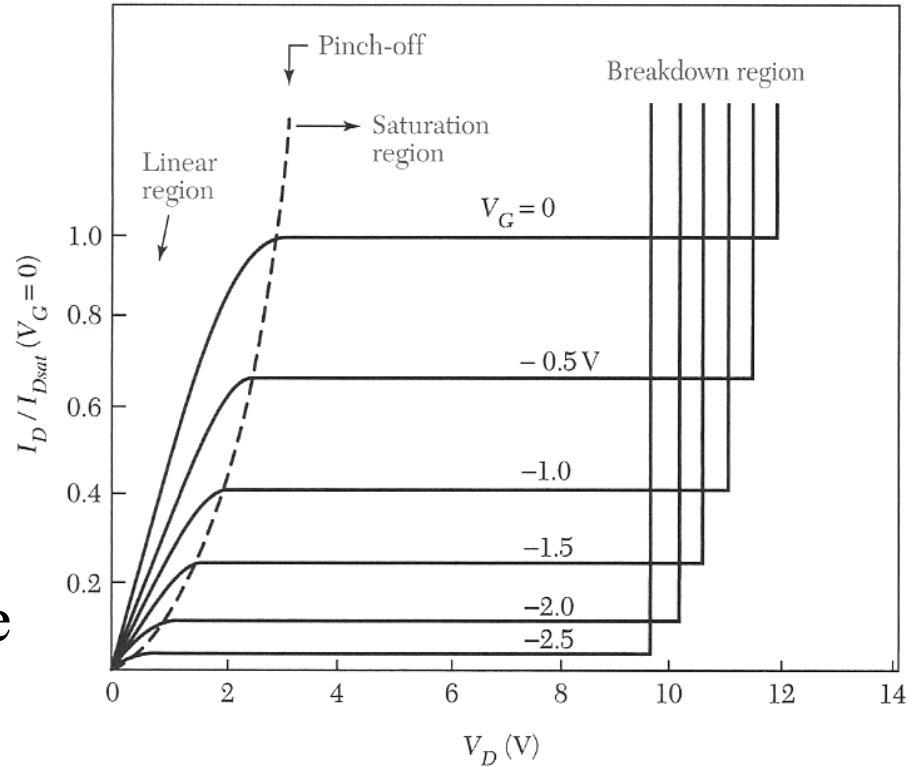
$$V_{sat} = V_p - V_{bi} + V_G$$

$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

$$I_{sat} = I_p \left[\frac{1}{3} - \frac{V_{bi} - V_G}{V_p} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

No V_D dependence

Voltage controlled current source



JFET - transconductance

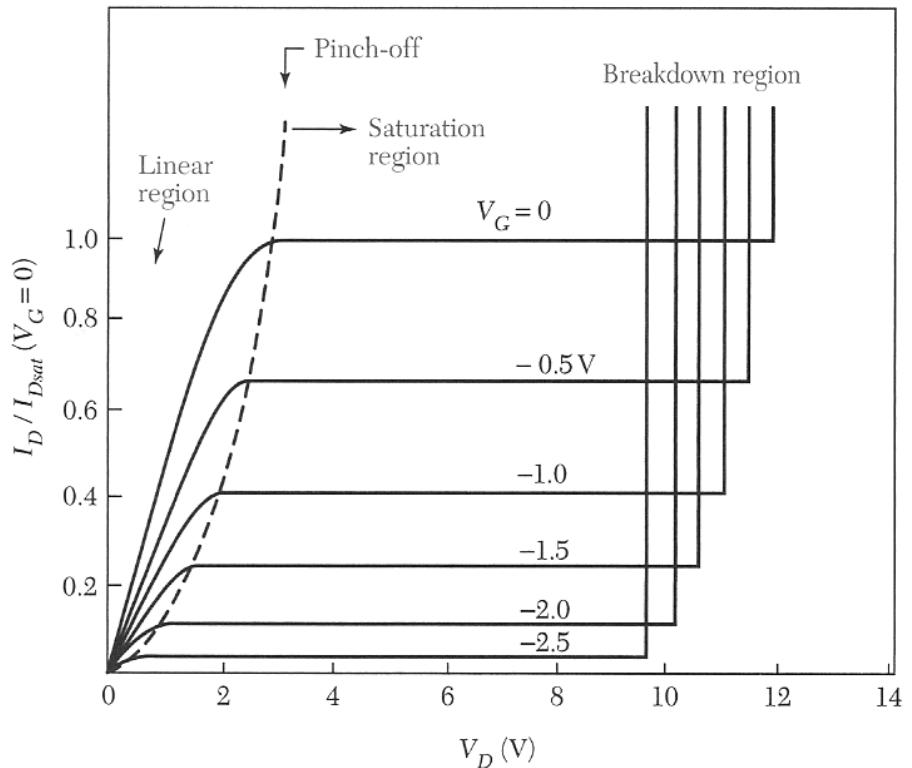
In the saturation regime,

$$I_{sat} = I_p \left[\frac{1}{3} - \frac{V_{bi} - V_G}{V_p} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$

transconductance (describes how good the voltage controlled current source is)

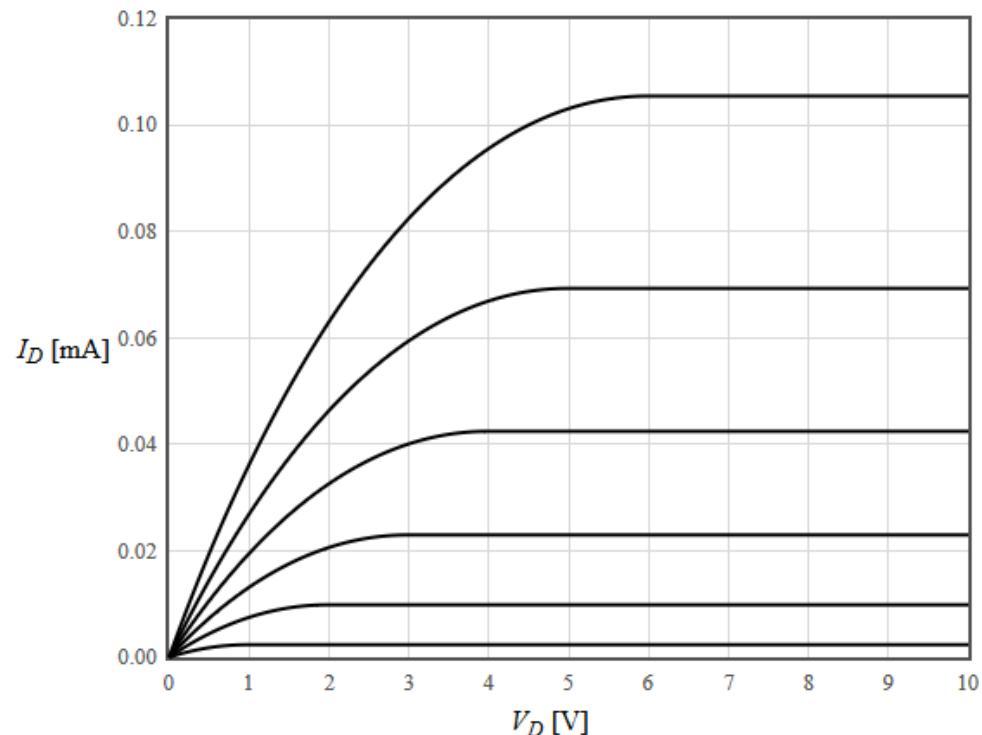
$$\downarrow \\ g_m = \frac{dI_{sat}}{dV_G} = \frac{I_p}{V_p} \left(1 - \sqrt{\frac{V_{bi} - V_G}{V_p}} \right)$$

$$g_m = \frac{dI_{sat}}{dV_G} = \frac{2Z\mu_n e N_D h}{L} \left(1 - \sqrt{\frac{V_{bi} - V_G}{V_p}} \right)$$



JFET

$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$



$$N_c(300K) = 2.78E19 \text{ cm}^{-3}$$

$$N_v(300K) = 9.84E18 \text{ cm}^{-3}$$

$$E_g = 1.166 - 4.73E-4 * T^2 / (T + 636) \text{ eV}$$

$$N_D = 1E15 \text{ cm}^{-3}$$

$$N_A = 1E19 \text{ cm}^{-3}$$

$$\mu_n = 1350 \text{ cm}^2/\text{Vs}$$

$$h = 3 \mu\text{m}$$

$$L = 100 \mu\text{m}$$

$$Z = 100 \mu\text{m}$$

$$\epsilon_r = 11.9$$

$$T = 300 \text{ K}$$

$$V_D(\max) = 10 \text{ V}$$

$$V_g[1] = 0 \text{ V}$$

$$V_g[2] = -1 \text{ V}$$

$$V_g[3] = -2 \text{ V}$$

$$V_g[4] = -3 \text{ V}$$

$$V_g[5] = -4 \text{ V}$$

$$V_g[6] = -5 \text{ V}$$

Replot

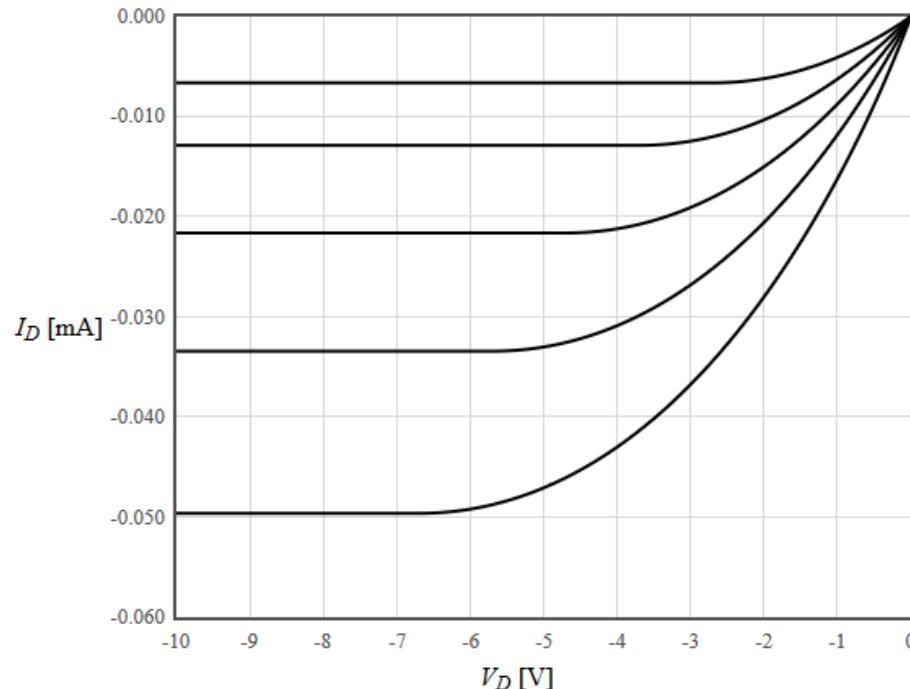
Si Ge GaAs

$$E_g = 1.12 \text{ eV}; \quad n_i = 6.41E+9 \text{ cm}^{-3}; \quad V_{bi} = 0.856 \text{ V}; \quad I_p = 0.000444 \text{ A}; \quad V_p = 6.84 \text{ V}.$$

p-channel JFET

The expression for the drain current of a p-channel JFET in the linear regime is,

$$I_D = I_p \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_{bi} + V_D - V_G}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_{bi} - V_G}{V_p} \right)^{3/2} \right]$$



$N_c(300K) =$	2.78E19	cm^{-3}
$N_v(300K) =$	9.84E18	cm^{-3}
$E_g =$	1.166-4.73E-4*T*T/(T+636)	eV
$N_D =$	1E19	cm^{-3}
$N_A =$	1E15	cm^{-3}
$\mu_p =$	480	cm^2/Vs
$h =$	3	μm
$L =$	100	μm
$Z =$	100	μm
$\epsilon_r =$	11.9	
$T =$	300	K
$V_D(\min) =$	-10	V
$V_g [1] =$	0	V
$V_g [2] =$	1	V
$V_g [3] =$	2	V
$V_g [4] =$	3	V
$V_g [5] =$	4	V
$V_g [6] =$	5	V

$$E_g = 1.12 \text{ eV}; \quad n_i = 6.41\text{e}+9 \text{ cm}^{-3}; \quad V_{bi} = 0.856 \text{ V}; \quad I_p = -0.000158 \text{ A}; \quad V_p = -6.84 \text{ V}.$$

High frequencies

$$\tilde{i}_{in} = 2\pi f C_G \tilde{v}_G$$

$$\tilde{i}_{out} = g_m \tilde{v}_G$$

for gain: $\tilde{i}_{in} < \tilde{i}_{out}$

$$f < \frac{g_m}{2\pi C_G} = f_T$$

f_T is the frequency
where the gain drops
below 1

average capacitance:

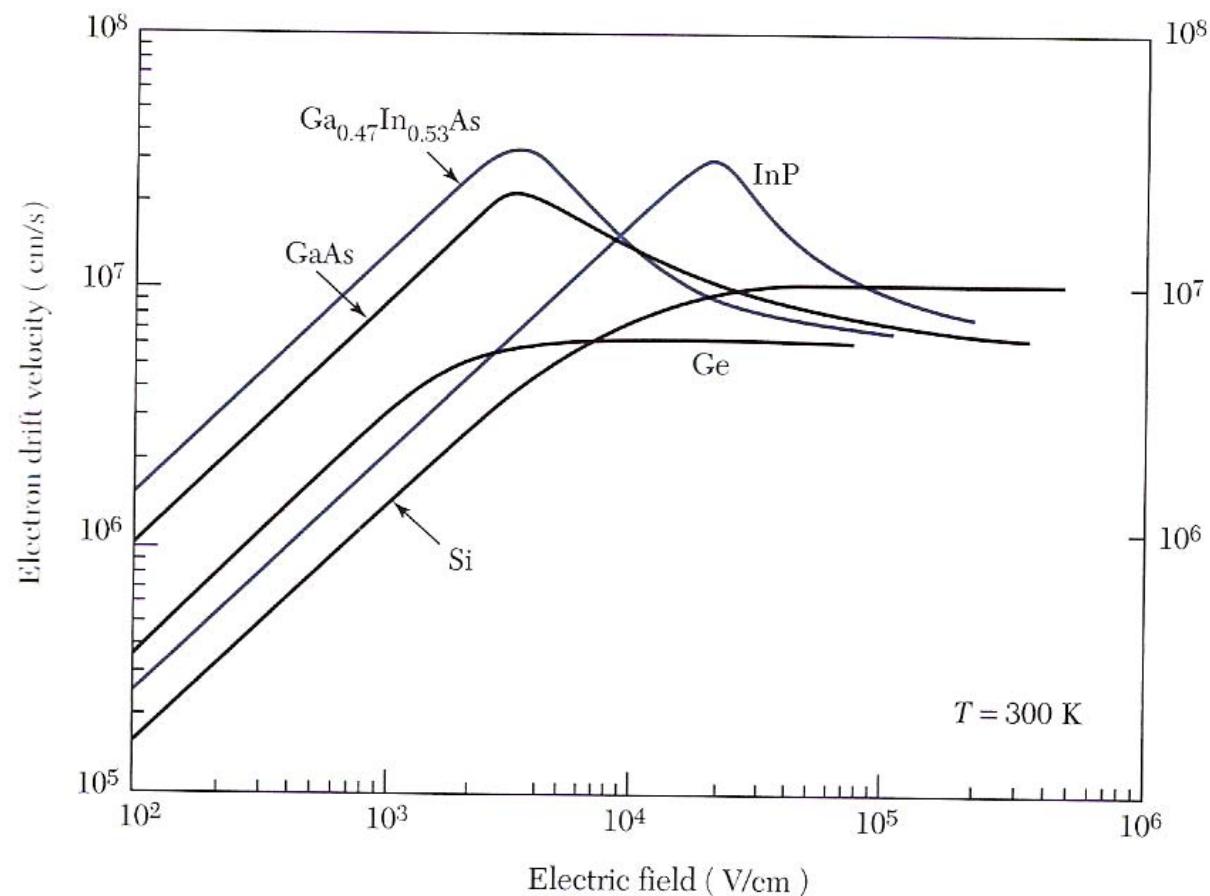
$$C_G = ZL \frac{\epsilon}{\bar{x}_n}$$

$$f_T = \frac{\mu_n e N_D h^2}{2\pi \epsilon L^2}$$

For velocity saturation, the approximation $dV = I_D \frac{\rho dy}{Z(h - x_n(y))}$ is not valid

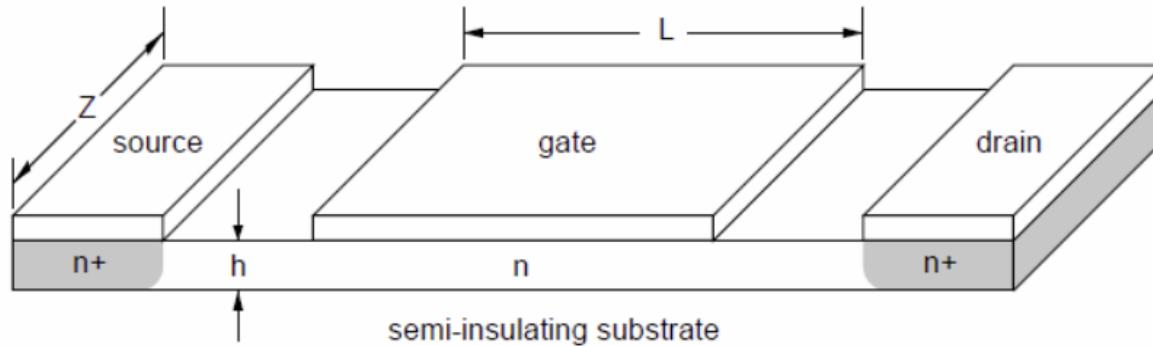
Ohm's law assumes $v_d = \mu E$

$$f_T \approx \frac{v_s}{L}$$

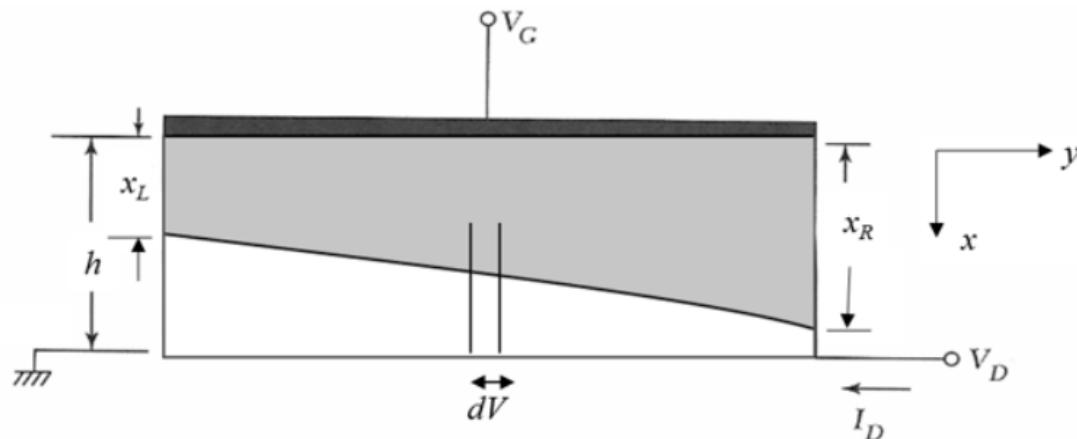


MESFET Gradual Channel Approximation

The description of a MESFET in the gradual channel approximation is almost the same as for a [JFET](#). The difference is how the built-in voltage V_{bi} is calculated. Consider an n -channel MESFET.



A MESFET consists of a semiconducting channel contacted by two ohmic contacts. The metal gate forms a Schottky contact above the channel. The current in the channel flows between the depletion layer of the Schottky diode and a semi-insulating substrate. When the Schottky contact is reverse biased, the depletion width expands and the channel becomes narrower. The thickness of the conducting channel is $h - x_n(y)$ where h is the thickness of the n -doped channel and $x_n(y)$ is the depletion width that depends on the position y along the channel. In the figure below, the gray region of the channel is depleted.



JFET/MESFET

JFET: small gate current (reverse leakage of the gate-to-channel junction)

More gate leakage than MOSFET, less than bipolar.

JFET has higher transconductance than the MOSFET.

Used in low-noise, high input-impedance op-amps and sometimes used in switching applications.

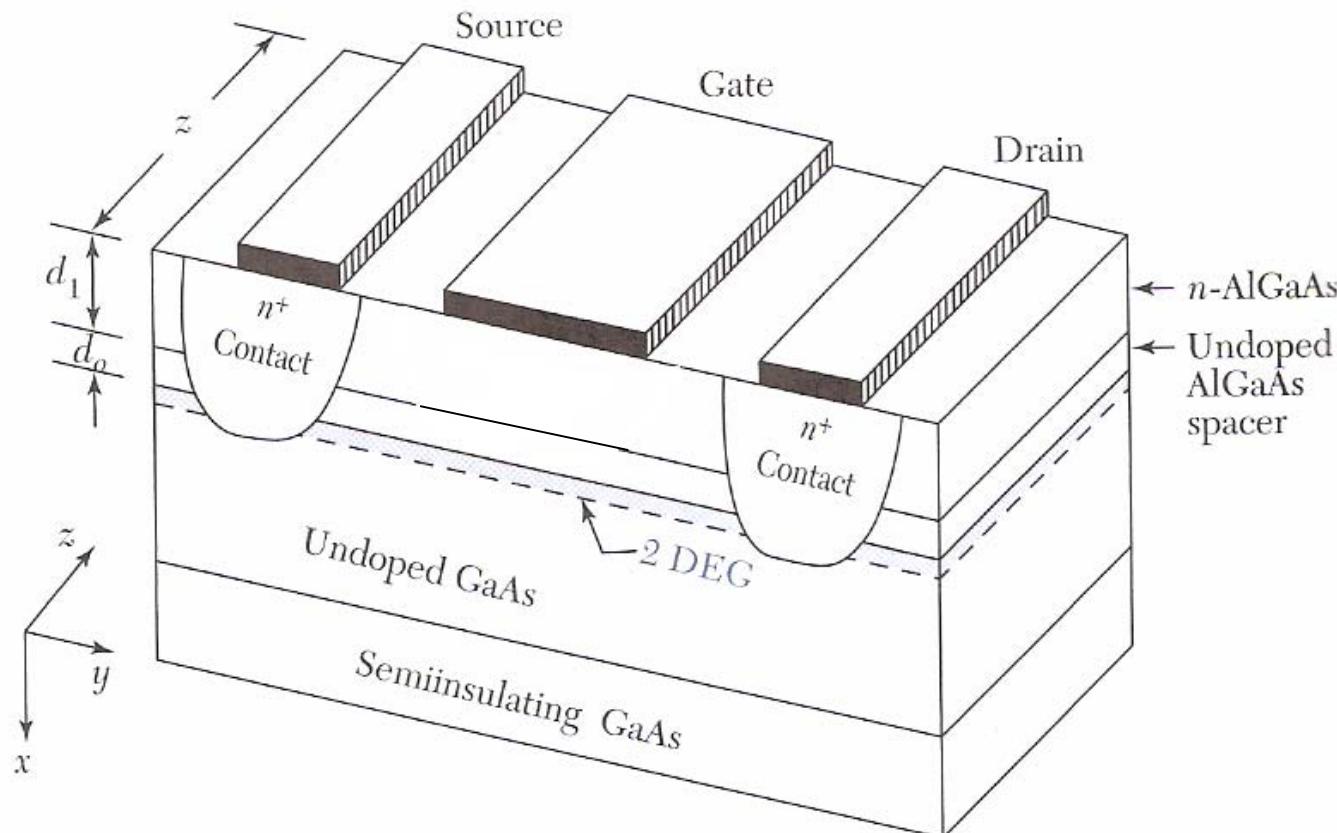
MESFET: usually constructed in compound semiconductor technologies lacking high quality surface passivation such as GaAs, InP, or SiC, and are faster but more expensive than silicon-based JFETs or MOSFETs.

Production MESFETs are operated up to approximately 30 GHz, and are commonly used for microwave frequency communications and radar.

Majority carrier device (like Schottky diode).

MODFET (HEMT)

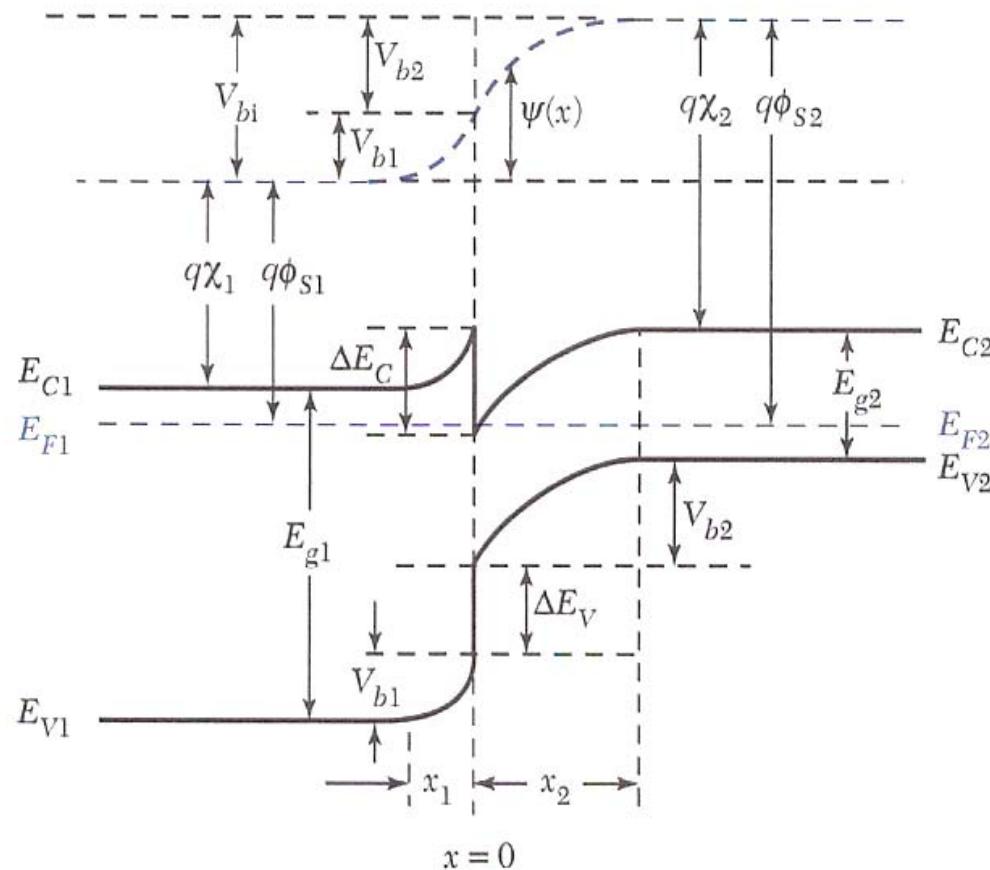
Modulation doped field effect transistor (MODFET)
High electron mobility transistor (HEMT)



V_T = Threshold voltage = voltage where charge is depleted

Heterostructure

pn junction formed from two semiconductors with different band gaps



MODFET/HEMT

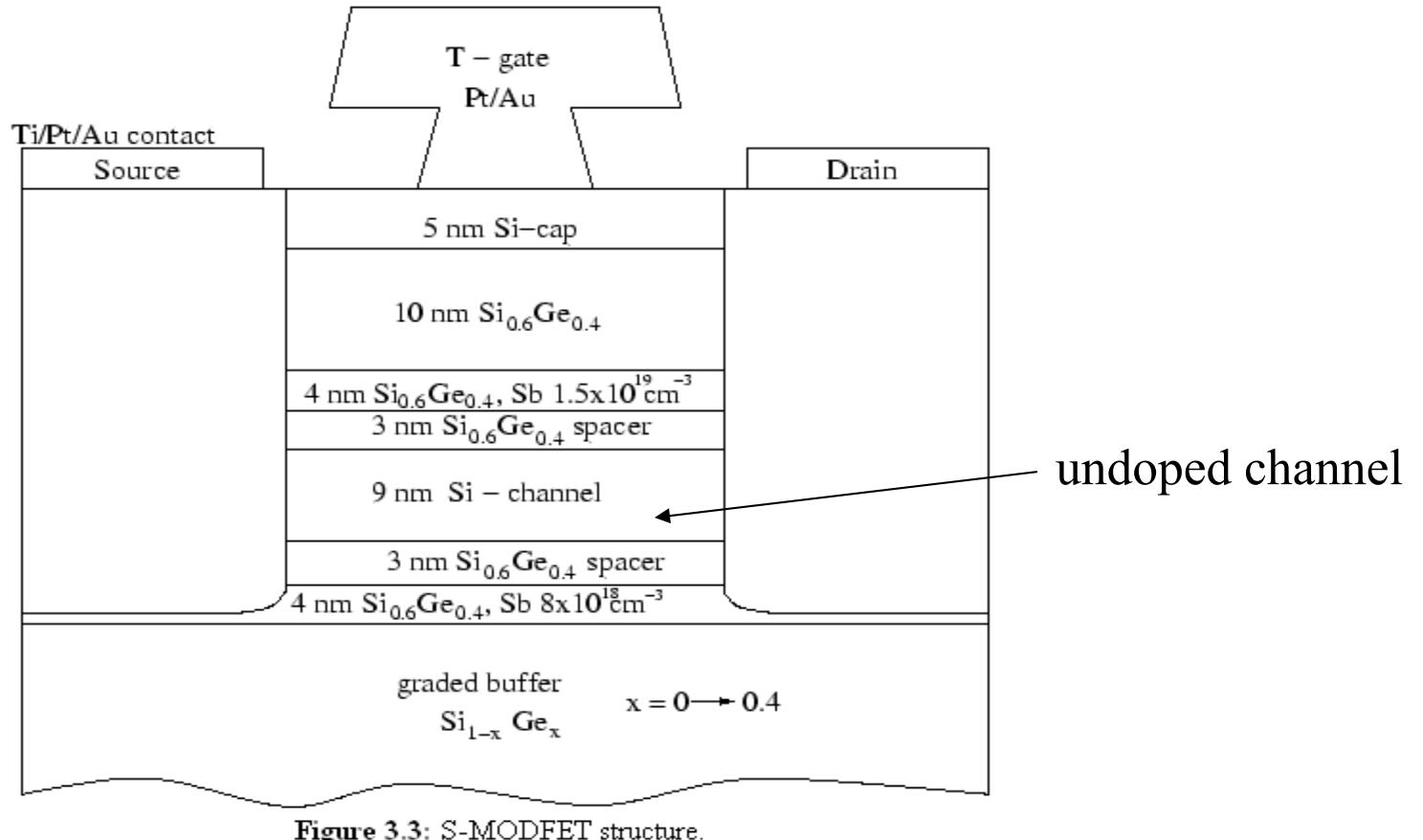


Figure 3.3: S-MODFET structure.

HEMT: HEMT devices are found in cell phones, electronic warfare systems, microwave and millimeter wave communications, radar, and radio astronomy.

PhD Thesis Sergey Smirnov

<http://www.iue.tuwien.ac.at/phd/smirnov/node71.html>

MODFET (HEMT)

$$j = nev_d = ne\mu_n E_y$$

$$I = jZt = Ze\mu_n n_s E_y$$

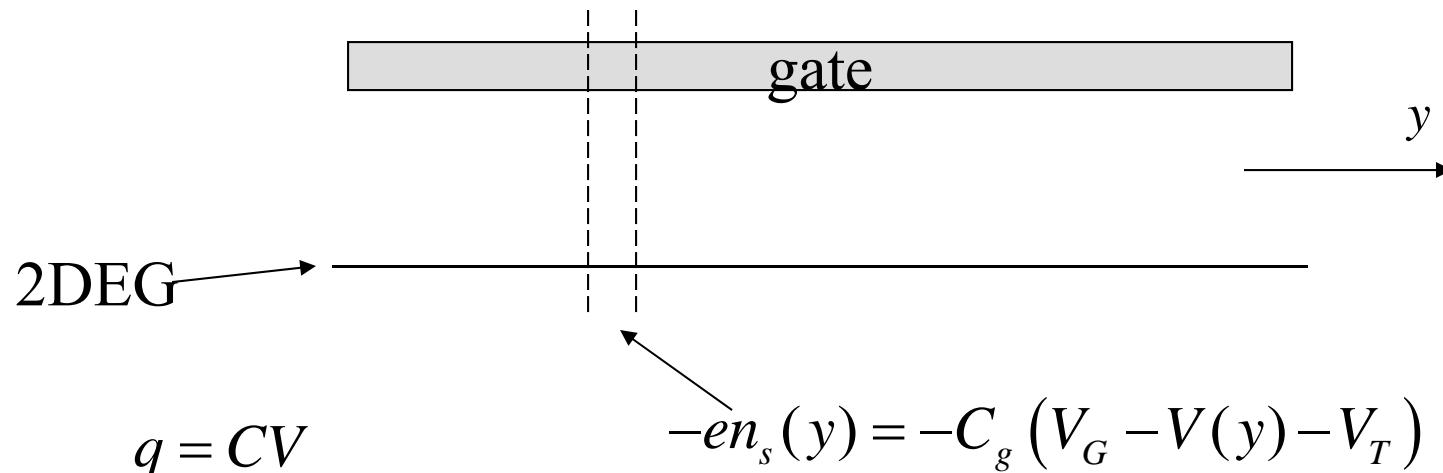
$$n = \frac{n_s}{t}$$

t is the thickness of the 2DEG

n_s is the sheet charge at the interface in C/cm².

$V_G - V(y)$ is the voltage between the gate and the 2DEG

$$n_s = 0 \text{ when } V_G - V(y) = V_T$$



MODFET (HEMT)

$-en_s(y) = C_g(V_G - V_B(y) - V_T)$ is the charge on the 2DEG at point y

The charge is zero when $V_G - V_B(y) = V_T$

solve for n_s

$$n_s(y) = \frac{-C_g(V_G - V_B(y) - V_T)}{e}$$

Substitute this in Ohm's law:

$$I = jZt = Ze\mu_n n_s E_y$$

MODFET (HEMT)

$$I = jZt = Ze\mu_n n_s E_y$$

$$n_s(y) = \frac{-C_g(V_G - V(y) - V_T)}{e}$$

substitute n_s in the top equation and substitute

$$E_y = \frac{-dV(y)}{dy}$$

$$I = Z\mu_n C(V_G - V_T - V(y)) \frac{dV(y)}{dy}$$

integrate along the length of the channel

$$\int_0^L Idy = \int_0^{V_D} Z\mu_n C(V_G - V_T - V(y)) dV$$

$$I_D = \frac{Z}{L} \mu_n C \left[(V_G - V_T) V_D - \frac{V_D^2}{2} \right]$$

MODFET (HEMT)

$$I = \frac{Z}{L} \mu_n C \left[(V_G - V_T) V_D - \frac{V_D^2}{2} \right]$$

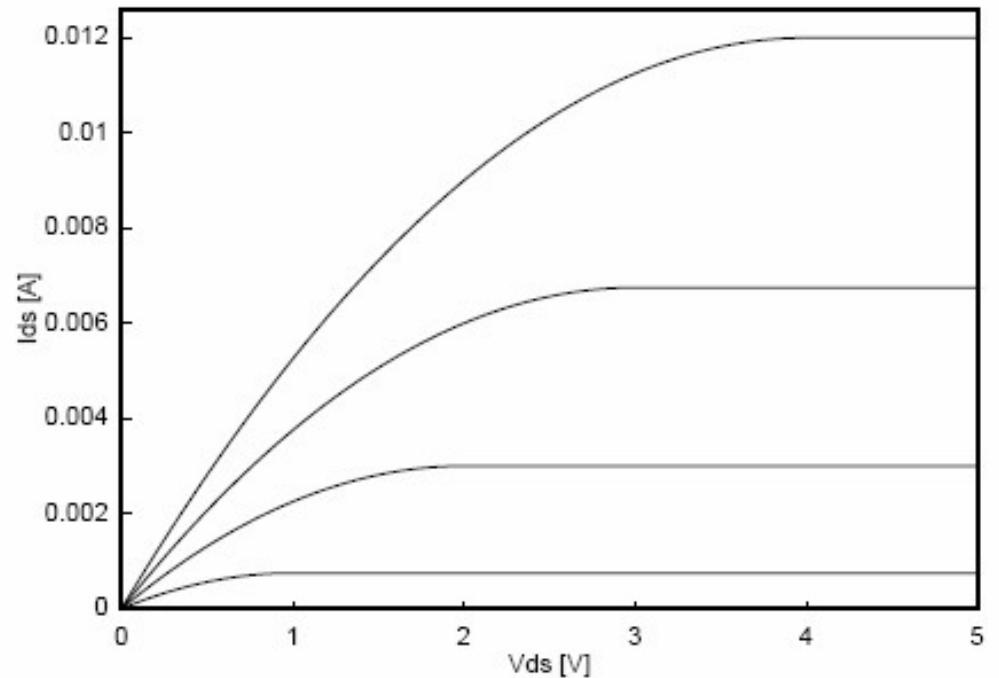
$$\frac{dI}{dV_D} = \frac{Z}{L} \mu_n C \left[(V_G - V_T) - V_D \right] = 0$$

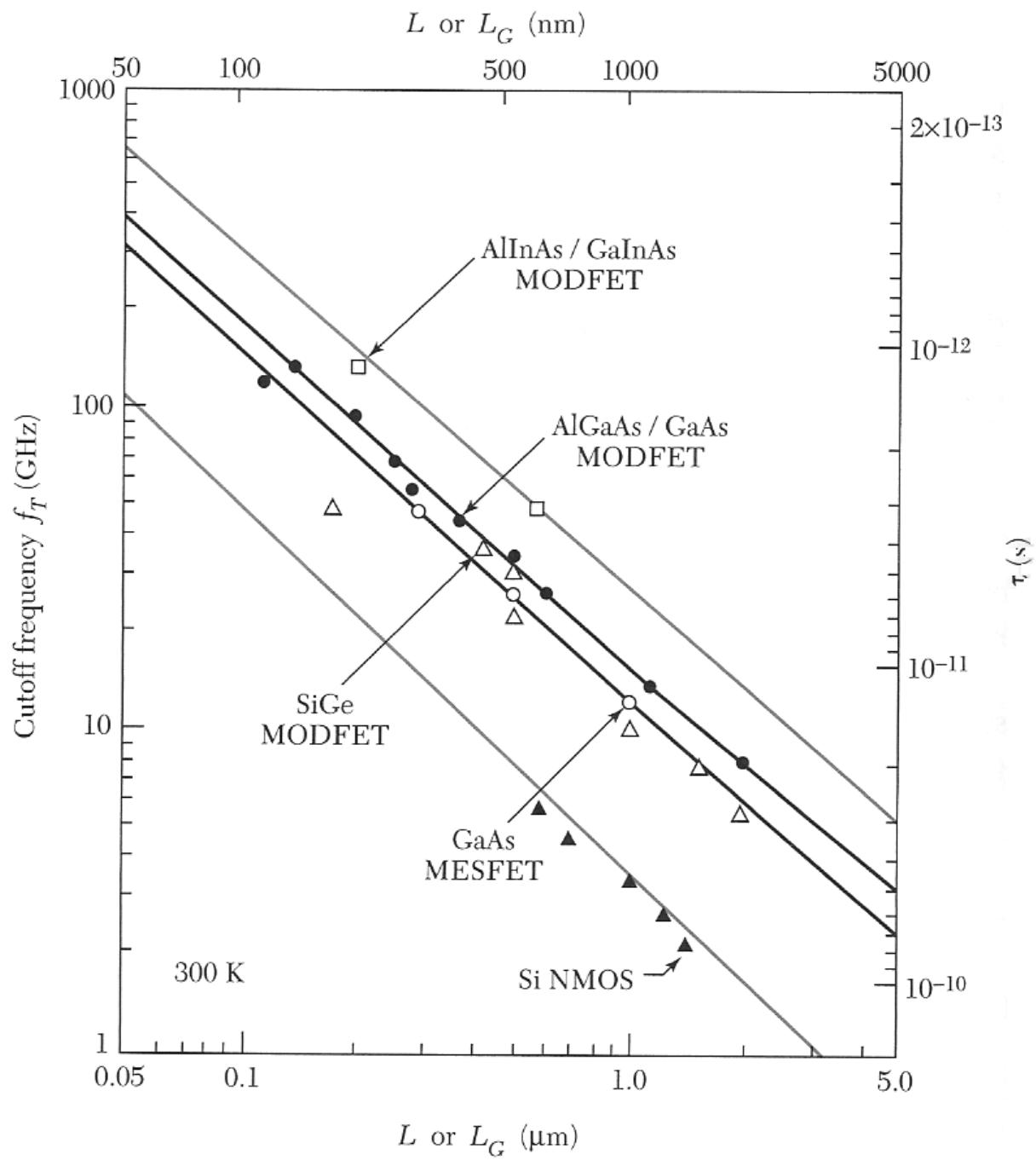
Set the derivative = 0 to find saturation voltage

$$V_{sat} = (V_G - V_T)$$

Substitute the saturation voltage into the formula at the top to find saturation current

$$I_{sat} = \frac{Z}{2L} \mu_n C (V_G - V_T)^2$$





MODFET/HEMT

HEMT: HEMT devices are found in many types of equipment ranging from cell phones and DBS receivers to electronic warfare systems, microwave and millimeter wave communications, radar, and radio astronomy. 600 GHz

